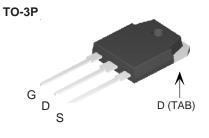


### FQA48N20-VB Datasheet

## N-Channel 200-V (D-S) MOSFET

| PRODUCT SUMMARY          |                                      |    |                       |  |
|--------------------------|--------------------------------------|----|-----------------------|--|
| V <sub>(BR)DSS</sub> (V) | $R_{DS(on)}(\Omega) \qquad I_{D}(A)$ |    | Q <sub>g</sub> (Typ.) |  |
| 200                      | 0.048 at V <sub>GS</sub> = 15 V      | 60 | 57                    |  |
| 200                      | 0.046 at V <sub>GS</sub> = 10 V      | 55 | 57                    |  |

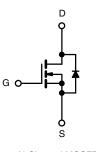


#### **FEATURES**

- Trench Power MOSFETS
- 175 °C Junction Temperature
- 100 % R<sub>g</sub> and UIS Tested •

#### **APPLICATIONS**

- Power Supply
- Lighting Systems



N-Channel MOSFET

| <b>ABSOLUTE MAXIMUM RATINGS</b>                      | $T_A = 25 \ ^{\circ}C$ , unless oth | erwise noted                      |                  |     |
|------------------------------------------------------|-------------------------------------|-----------------------------------|------------------|-----|
| Parameter                                            | Symbol                              | Limit                             | Unit             |     |
| Drain-Source Voltage                                 | V <sub>DS</sub>                     | 200                               | v                |     |
| Gate-Source Voltage                                  |                                     | V <sub>GS</sub>                   | ± 25             | v   |
| Continuous Drain Current ( $T_J = 175 \ ^{\circ}C$ ) | T <sub>C</sub> = 25 °C              | 1-                                | 60               |     |
|                                                      | T <sub>C</sub> = 100 °C             | I <sub>D</sub>                    | 40               | •   |
| Pulsed Drain Current                                 |                                     | I <sub>DM</sub>                   | 180              | - A |
| Single Pulse Avalanche Current                       | L = 0.1 mH                          | I <sub>AS</sub>                   | 20               |     |
| Single Pulse Avalanche Energy <sup>a</sup>           | L = 0.11111                         | E <sub>AS</sub>                   | 20               | mJ  |
| Maximum Power Dissipation <sup>a</sup>               | T <sub>C</sub> = 25 °C              | P                                 | 166 <sup>b</sup> | 14/ |
|                                                      | T <sub>A</sub> = 25 °C <sup>c</sup> | – P <sub>D</sub> –                | 3.12             | W   |
| Operating Junction and Storage Temperature Range     |                                     | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 175      | °C  |

| THERMAL RESISTANCE RATINGS                   |                   |       |      |  |
|----------------------------------------------|-------------------|-------|------|--|
| Parameter                                    | Symbol            | Limit | Unit |  |
| Junction-to-Ambient (PCB Mount) <sup>c</sup> | R <sub>thJA</sub> | 40    | °C/M |  |
| Junction-to-Case (Drain)                     | R <sub>thJC</sub> | 0.75  | °C/W |  |

Notes:

a. Duty cycle  $\leq$  1 %.

b. See SOA curve for voltage derating.

c. When Mounted on 1" square PCB (FR-4 material).

|   | 3    | ®   | Bs  | emi   |
|---|------|-----|-----|-------|
| W | ww.\ | /B: | sem | i.com |

| Parameter                                     | Symbol               | Test Conditions                                                                              | Min. | Тур.  | Max.  | Unit |  |
|-----------------------------------------------|----------------------|----------------------------------------------------------------------------------------------|------|-------|-------|------|--|
| Static                                        |                      |                                                                                              |      |       |       |      |  |
| Drain-Source Breakdown Voltage                | V <sub>(BR)DSS</sub> | $V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$                                      | 200  |       |       | v    |  |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub>  | $V_{DS} = V_{GS}, I_D = 250 \ \mu A$                                                         | 2.5  |       | 4.5   |      |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>     | $V_{DS} = 0 V, V_{GS} = \pm 20 V$                                                            |      |       | ± 100 | nA   |  |
|                                               |                      | $V_{DS} = 0 V, V_{GS} = \pm 25 V$                                                            |      |       | ± 300 |      |  |
| Zero Gate Voltage Drain Current               |                      | $V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$                                       |      |       | 1     | μA   |  |
|                                               | I <sub>DSS</sub>     | $V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 100 ^{\circ}\text{C}$ |      |       | 25    |      |  |
|                                               |                      | $V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 150 ^{\circ}\text{C}$ |      |       | 250   |      |  |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>   | $V_{DS} \ge 10 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$                                     | 40   |       |       | А    |  |
| Drain-Source On-State Resistance <sup>a</sup> |                      | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A                                                |      | 0.048 |       | 1    |  |
|                                               | Б                    | V <sub>GS</sub> = 15 V, I <sub>D</sub> = 20 A                                                |      | 0.046 |       | Ω    |  |
|                                               | R <sub>DS(on)</sub>  | $V_{GS}$ = 10 V, $I_{D}$ = 20 A, $T_{J}$ = 100 °C                                            |      | 0.088 |       |      |  |
|                                               |                      | $V_{GS}$ = 10 V, $I_{D}$ = 20 A, $T_{J}$ = 150 °C                                            |      | 0.120 |       | 1    |  |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>      | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A                                                | 25   |       |       | S    |  |
| Dynamie <sup>®</sup>                          | 4                    |                                                                                              |      | •     |       |      |  |
| Input Capacitance                             | C <sub>iss</sub>     |                                                                                              |      | 3100  |       | pF   |  |
| Output Capacitance                            | C <sub>oss</sub>     | $V_{GS}$ = 0 V, $V_{DS}$ = 25 V, f = 1 MHz                                                   |      | 300   |       |      |  |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>     |                                                                                              |      | 135   |       |      |  |
| •                                             |                      | $V_{DS} = 100 \text{ V}, V_{GS} = 15 \text{ V}, I_{D} = 50 \text{ A}$                        | 85   |       | 127   | 1    |  |
| Total Gate Charge <sup>c</sup>                | Qg                   |                                                                                              |      | 57    | 85    |      |  |
| Gate-Source Charge <sup>c</sup>               | Q <sub>gs</sub>      | $V_{DS}$ = 100 V, $V_{GS}$ = 10 V, $I_{D}$ = 50 A                                            |      | 14    |       | nC   |  |
| Gate-Drain Charge <sup>c</sup>                | Q <sub>gd</sub>      |                                                                                              |      | 20    |       |      |  |
| Gate Resistance                               | R <sub>g</sub>       | f = 1 MHz                                                                                    | 1.2  |       | 1.8   | Ω    |  |
| Turn-On Delay Time <sup>c</sup>               | t <sub>d(on)</sub>   |                                                                                              |      | 16    | 25    |      |  |
| Rise Time <sup>c</sup>                        | t <sub>r</sub>       | $V_{DD}$ = 100 V, $R_L$ = 2 $\Omega$                                                         |      | 170   | 260   |      |  |
| Turn-Off Delay Time <sup>c</sup>              | t <sub>d(off)</sub>  | ${ m I}_{ m D}\cong$ 50 A, ${ m V}_{ m GEN}$ = 10 V, ${ m R}_{ m g}$ = 1 $\Omega$            |      | 27    | 42    | - ns |  |
| Fall Time <sup>c</sup>                        | t <sub>f</sub>       |                                                                                              |      | 9     | 18    |      |  |
| Source=DrainDiord=Flatings=and=Ofa            | Teacteristics        |                                                                                              |      |       |       |      |  |
| Continuous Current                            | I <sub>S</sub>       |                                                                                              |      |       | 36    |      |  |
| Pulsed Current                                | I <sub>SM</sub>      |                                                                                              |      |       | 80    | A    |  |
| Forward Voltage <sup>a</sup>                  | V <sub>SD</sub>      | I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V                                                 |      | 0.86  | 1.5   | V    |  |
| Reverse Recovery Time                         | t <sub>rr</sub>      |                                                                                              |      | 116   | 175   | ns   |  |
| Peak Reverse Recovery Current                 | I <sub>RM(REC)</sub> |                                                                                              |      | 9     | 14    | А    |  |
| Reverse Recovery Charge                       | Q <sub>rr</sub>      | I <sub>F</sub> = 40 A, di/dt = 100 A/μs                                                      |      | 0.53  | 0.8   | μC   |  |
| Reverse Recovery Fall Time                    | t <sub>a</sub>       |                                                                                              |      | 84    |       |      |  |
| Reverse Recovery Rise Time                    | t <sub>b</sub>       |                                                                                              |      | 32    |       | nS   |  |

Notes:

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

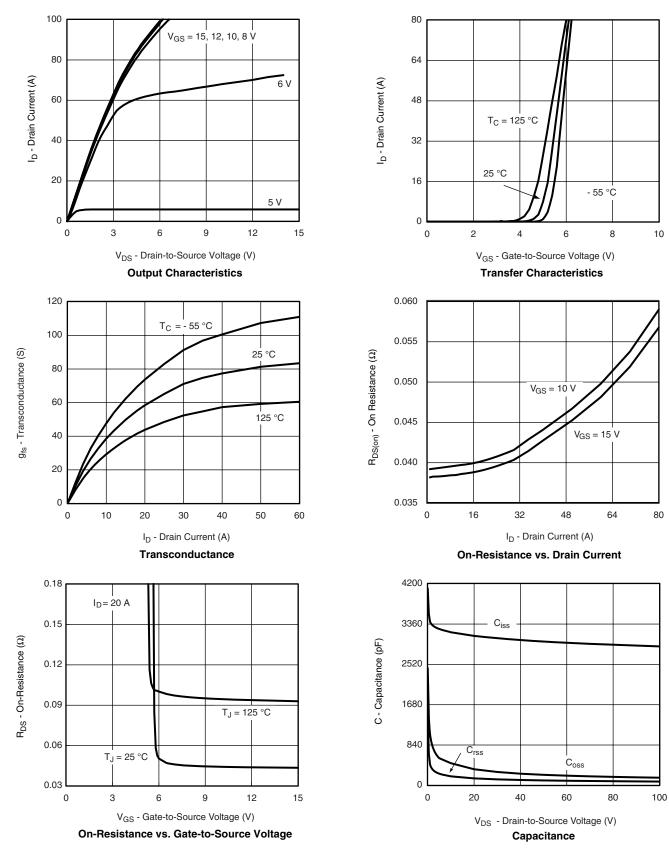
b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

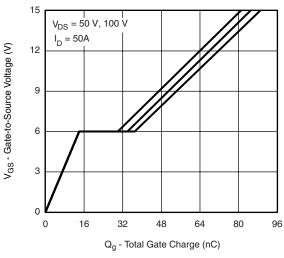




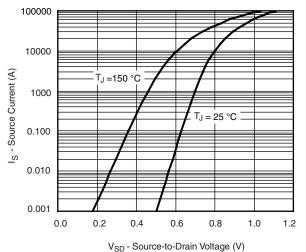


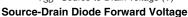


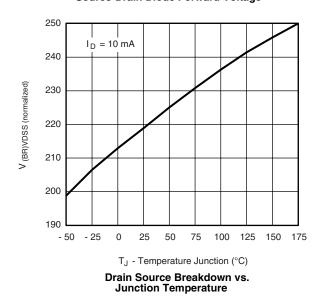
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

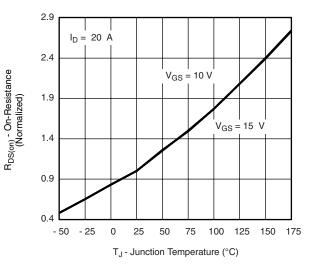




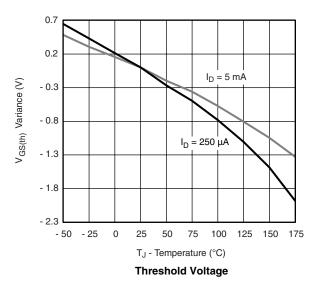


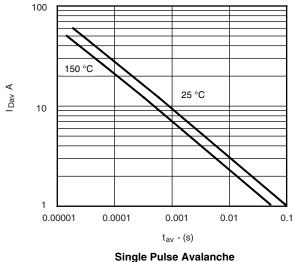


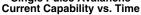




**On-Resistance vs. Junction Temperature** 



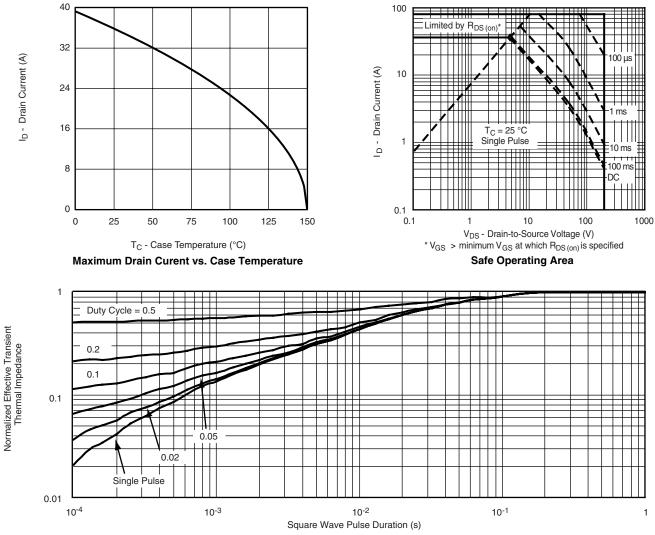




## FQA48N20-VB



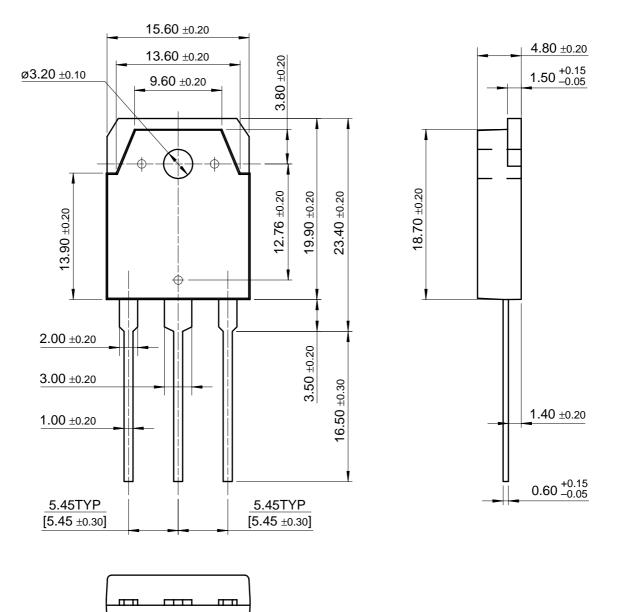
#### **THERMAL RATINGS**



Normalized Thermal Transient Impedance, Junction-to-Case



TO-3P





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